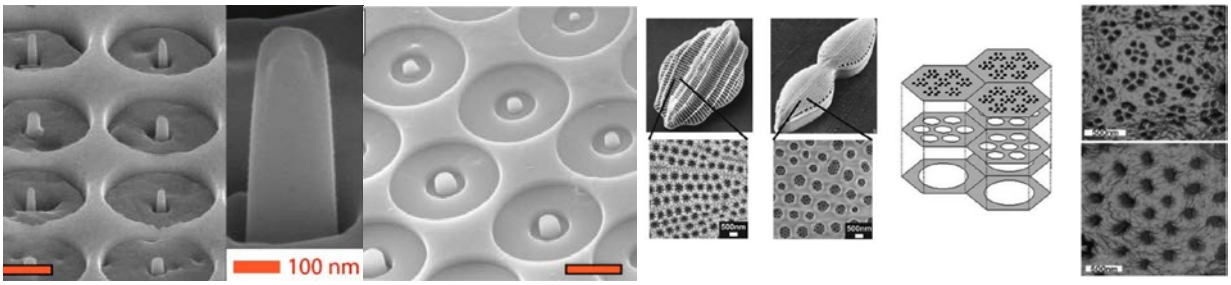

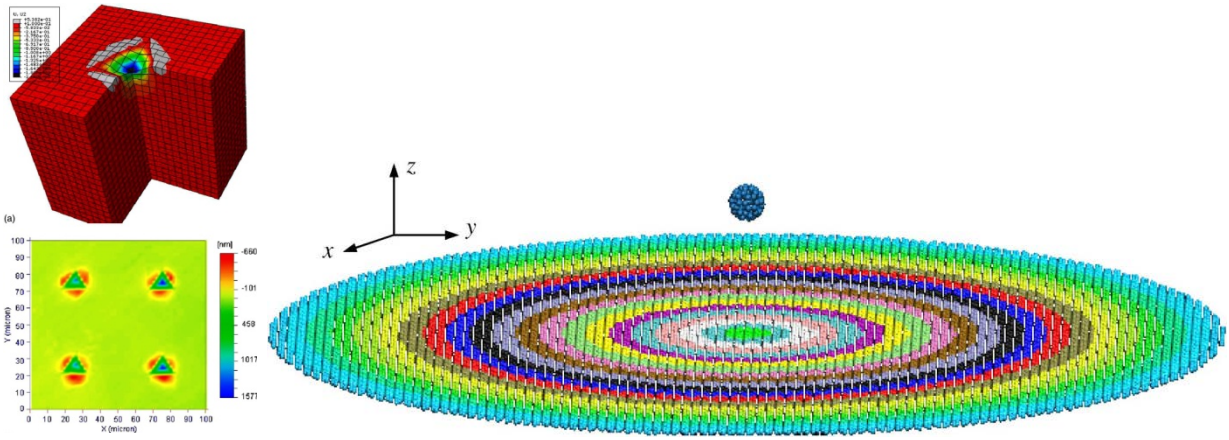

ASCE JOURNAL OF NANOMECHANICS AND MICROMECHANICS

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Publication Date: December 15, 2013